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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Po-Yao Lin et al

Serial No: 09/379,599

Filed: August 24, 1999

For: Integrated Circuit Package with  
Multiple Heat Dissipation Paths



Art Unit: 2835

Examiner: Chervinsky, B.

Atty Docket: 0694/00063

**SUBMISSION OF FORMAL DRAWINGS**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In accordance with the Notice of Allowability mailed September 27, 2000,  
Applicants submit herewith 1 sheet of formal drawings of Figs. 1-3.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Burton A. Amernick".

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Date: 11-07-00